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## FQP47P06 P-Channel QFET<sup>®</sup> MOSFET

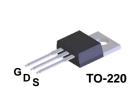
## - 60 V, - 47 A, 26 mΩ

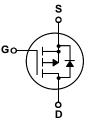
### Description

This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconducto®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

## Features

- 47 A, 60 V, R<sub>DS(on)</sub> = 26 m $\Omega$  @ V<sub>GS</sub> = 10 V, I<sub>D</sub> = - 23.5 A
- Low Gate Charge (Typ. 84 nC)
- Low Crss ( yp. 320 pF)
- 100% Avalanche Tested
- 175°C Maximum Junction Temrature Rating.





## Absolute Maximum Ratings T<sub>c</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQP47P06	Unit
V <sub>DSS</sub>	Drain-Source Voltage		-60	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		-47	А
	- Continuous (T <sub>C</sub> = 100	D°C)	-33.2	А
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	-188	А
V <sub>GSS</sub>	Gate-Source Voltage		± 25	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	820	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	-47	А
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	16	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-7.0	V/ns
PD	Power Dissipation ( $T_C = 25^{\circ}C$ )		160	W
	- Derate above 25°C		1.06	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +175	°C
T	Maximum lead temperature for soldering	g purposes,	300	°C
'L	1/8" from case for 5 seconds		300	C

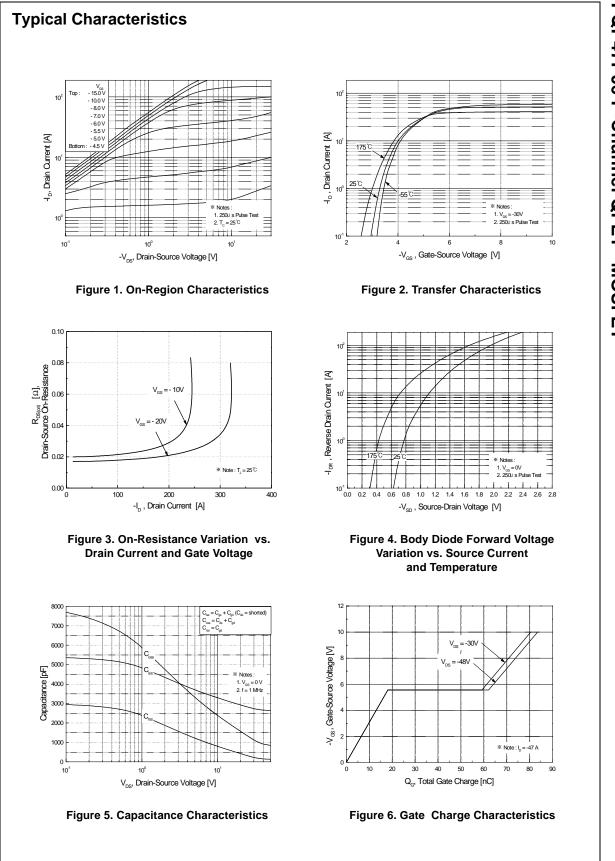
## **Thermal Characteristics**

Symbol	Parameter	FQP47P06	Unit
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction-to-Case, Max.	0.94	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

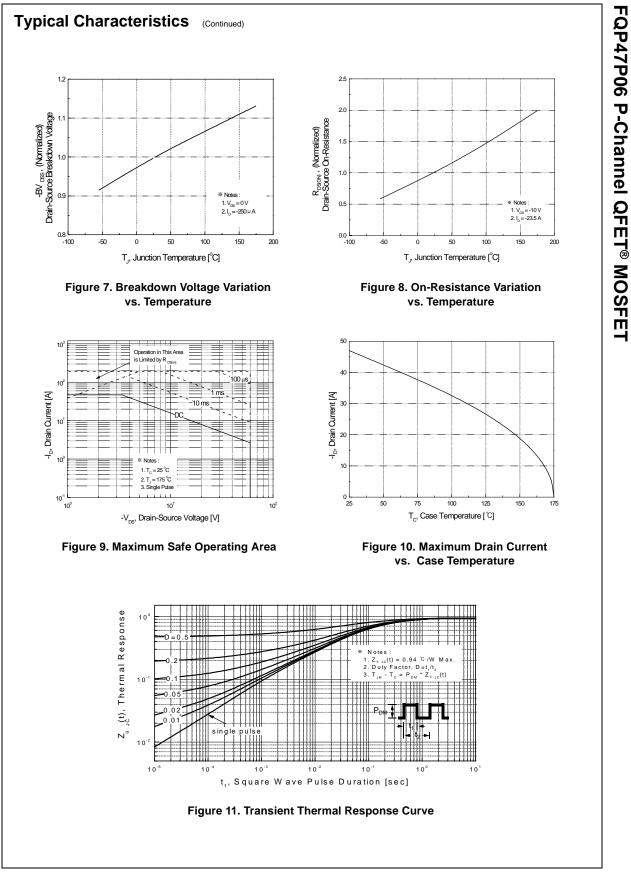
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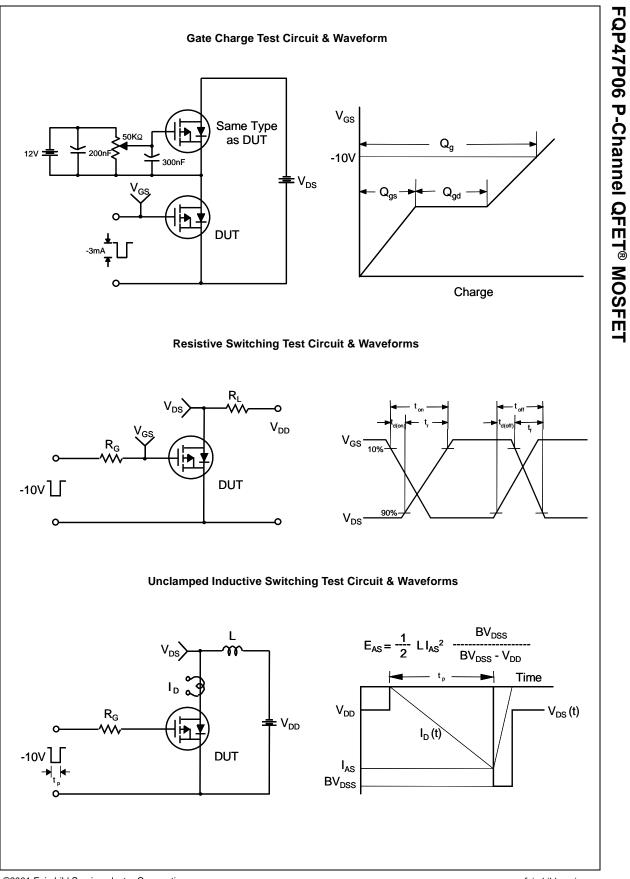
eristics n-Source Breakdown Voltage akdown Voltage Temperature fficient o Gate Voltage Drain Current e-Body Leakage Current, Forwar e-Body Leakage Current, Revers eristics e Threshold Voltage ic Drain-Source Resistance		-60   	 -0.06    	 1 -10 -100 100	V V/°C μΑ μΑ nA
n-Source Breakdown Voltage akdown Voltage Temperature fficient o Gate Voltage Drain Current e-Body Leakage Current, Forwar e-Body Leakage Current, Revers eristics e Threshold Voltage ic Drain-Source	$I_{D} = -250 \ \mu\text{A}, \text{ Referenced to } 25^{\circ}\text{C}$ $V_{DS} = -60 \ \text{V}, \ V_{GS} = 0 \ \text{V}$ $V_{DS} = -48 \ \text{V}, \ T_{C} = 150^{\circ}\text{C}$ $V_{GS} = -25 \ \text{V}, \ V_{DS} = 0 \ \text{V}$ $V_{GS} = 25 \ \text{V}, \ V_{DS} = 0 \ \text{V}$		-0.06   	 -1 -10 -100	V/°C μA μA nA
akdown Voltage Temperature fficient o Gate Voltage Drain Current e-Body Leakage Current, Forwai e-Body Leakage Current, Revers eristics e Threshold Voltage ic Drain-Source	$I_{D} = -250 \ \mu\text{A}, \text{ Referenced to } 25^{\circ}\text{C}$ $V_{DS} = -60 \ \text{V}, \ V_{GS} = 0 \ \text{V}$ $V_{DS} = -48 \ \text{V}, \ T_{C} = 150^{\circ}\text{C}$ $V_{GS} = -25 \ \text{V}, \ V_{DS} = 0 \ \text{V}$ $V_{GS} = 25 \ \text{V}, \ V_{DS} = 0 \ \text{V}$			-1 -10 -100	μA μA nA
e-Body Leakage Current, Forwar e-Body Leakage Current, Revers eristics e Threshold Voltage ic Drain-Source	$V_{DS} = -48 \text{ V}, T_{C} = 150^{\circ}\text{C}$ $d  V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$ $e  V_{GS} = 25 \text{ V}, V_{DS} = 0 \text{ V}$			-10 -100	μA nA
e-Body Leakage Current, Forwar e-Body Leakage Current, Revers eristics e Threshold Voltage ic Drain-Source				-100	nA
e-Body Leakage Current, Revers eristics e Threshold Voltage ic Drain-Source	e V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V				
eristics e Threshold Voltage ic Drain-Source		1		100	nA
e Threshold Voltage ic Drain-Source	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μA				
ic Drain-Source	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$				
		-2.0		-4.0	V
	$V_{GS}$ = -10 V, I <sub>D</sub> = -23.5 A		0.021	0.026	Ω
ward Transconductance	$V_{DS} = -30 \text{ V}, I_D = -23.5 \text{ A}$ (Note 4)		21		S
				·	
	$V_{DS} = -25 V, V_{GS} = 0 V,$				pF
1	f = 1.0 MHz				pF pF
n-On Delay Time	V <sub>DD</sub> = -30 V, I <sub>D</sub> = -23.5 A,		50	110	ns
n-On Rise Time	55 5		450	910	ns
n-Off Delay Time	1.6 - 20 - 2		100	210	ns
n-Off Fall Time	(Note 4, 5)		195	400	ns
	Vps = -48 V. lp = -47 A.				115
I Gate Charge	V <sub>DS</sub> = -48 V, I <sub>D</sub> = -47 A,		84	110	nC
Il Gate Charge e-Source Charge	$V_{DS} = -48 \text{ V}, \text{ I}_{D} = -47 \text{ A},$ $V_{GS} = -10 \text{ V}$		84 18	110 	
ů.			-	-	nC
e-Source Charge e-Drain Charge	V <sub>GS</sub> = -10 V (Note 4, 5)		18	-	nC nC
e-Source Charge	V <sub>GS</sub> = -10 V (Note 4, 5) and Maximum Ratings		18	-	nC nC
e-Source Charge e-Drain Charge ce Diode Characteristics	V <sub>GS</sub> = -10 V (Note 4, 5) and Maximum Ratings Diode Forward Current		18 44		nC nC nC
e-Source Charge e-Drain Charge <b>ce Diode Characteristics</b> imum Continuous Drain-Source	V <sub>GS</sub> = -10 V (Note 4, 5) and Maximum Ratings Diode Forward Current e Forward Current		18 44	  -47	nC nC nC
e-Source Charge e-Drain Charge <b>ce Diode Characteristics</b> imum Continuous Drain-Source imum Pulsed Drain-Source Dioc	V <sub>GS</sub> = -10 V (Note 4, 5) and Maximum Ratings Diode Forward Current e Forward Current		18 44  	  -47 -188	nC nC nC A A
	haracteristics ut Capacitance put Capacitance verse Transfer Capacitance Characteristics n-On Delay Time n-On Rise Time n-Off Delay Time n-Off Fall Time	ut Capacitance $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ put Capacitancef = 1.0 MHzverse Transfer CapacitancefCharacteristicsm-On Delay Time $V_{DD} = -30 \text{ V}, I_D = -23.5 \text{ A},$ m-On Rise Time $R_G = 25 \Omega$	ut Capacitance $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ put Capacitancef = 1.0 MHzverse Transfer CapacitanceCharacteristicsn-On Delay Time $V_{DD} = -30 \text{ V}, I_D = -23.5 \text{ A},$ n-On Rise Time $R_G = 25 \Omega$ n-Off Delay Time	ut Capacitance $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ 2800         put Capacitance       f = 1.0 MHz        1300         verse Transfer Capacitance        320         Characteristics         n-On Delay Time $V_{DD} = -30 \text{ V}, \text{ I}_D = -23.5 \text{ A},$ n-Off Delay Time $V_{GS} = 25 \Omega$ 50         n-Off Delay Time        100	ut Capacitance $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ 2800       3600         put Capacitance       f = 1.0 MHz        1300       1700         verse Transfer Capacitance        320       420         Characteristics         m-On Delay Time $V_{DD} = -30 \text{ V}, \text{ I}_D = -23.5 \text{ A},$ 50       110         m-Off Delay Time $R_G = 25 \Omega$ 450       910          100       210



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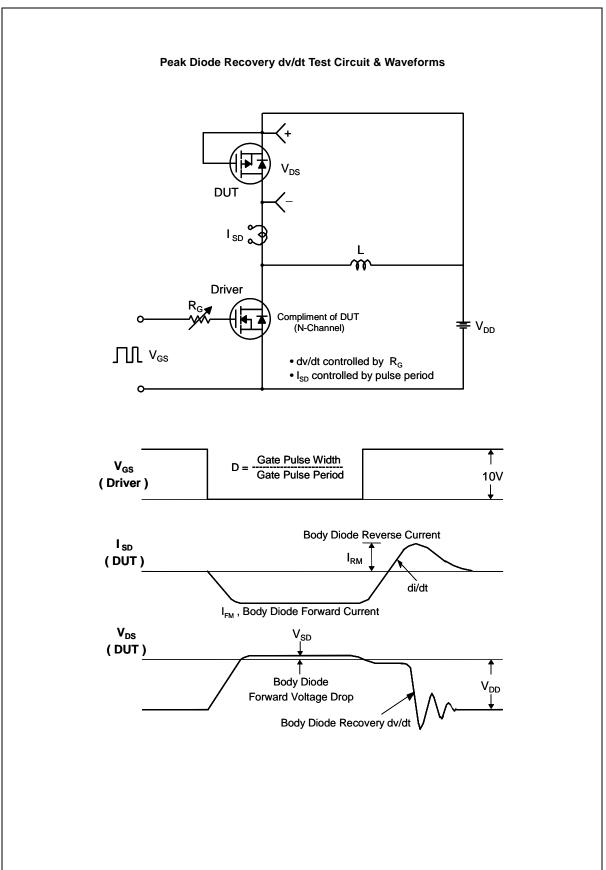


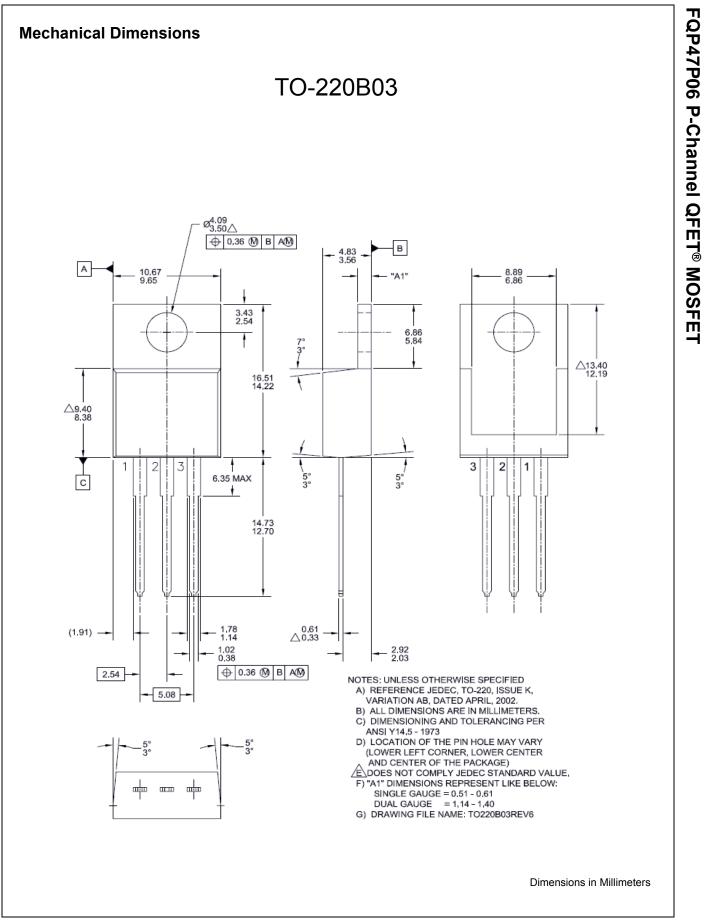
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